

Product / Process Change Notification



N° 2018-019-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of an additional mold compound for reverse conducting IGBT products in TO247 package.

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **19th July 2018**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "**JESD46**", which stipulates: "**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**"

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Dr. Eckart Süner
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

Product / Process Change Notification



N° 2018-019-A

► **Products affected:** Please refer to attached affected product list 1_cip18019A

► **Detailed Change Information:**

Subject: Introduction of an additional mold compound for reverse conducting IGBT products in TO247 package.

Reason: Implementation of 2nd source.

Description:	<u>Old</u>	<u>New</u>
Mold compound	Sumitomo EME E500 HA	Sumitomo EME E500 HA and Kyocera KE G300 BH

► **Product Identification:** Internal traceability assured via basic type, lot code and development code.
External traceability:
Sales code / SP number/ Product Barcode Label / Lot code

► **Impact of Change:** No impact on parameters and reliability as proven via product qualification.

► **Attachments:** Affected product list 1_cip18019A
Qualification report 2_cip18019A

► **Time Schedule:**

- Final qualification report: Available on request
- First samples available: 2018-05-31
- Intended start of delivery: 2018-09-15 or earlier after customer release

If you have any questions, please do not hesitate to contact your local Sales office.

PCN N° 2018-019-A

Introduction of an additional mold compound for reverse conducting IGBT products in TO247 package.



Sales name	SP number	OPN	Package
IHW15N120E1	SP001391908	IHW15N120E1XKSA1	PG-TO247-3
IHW15N120R3	SP000521590	IHW15N120R3FKSA1	PG-TO247-3
IHW20N120R3	SP000437702	IHW20N120R3FKSA1	PG-TO247-3
IHW20N120R5	SP001150026	IHW20N120R5XKSA1	PG-TO247-3
IHW20N135R3	SP000909532	IHW20N135R3FKSA1	PG-TO247-3
IHW20N135R5	SP001078568	IHW20N135R5XKSA1	PG-TO247-3
IHW25N120E1	SP001391910	IHW25N120E1XKSA1	PG-TO247-3
IHW25N120R2	SP000212016	IHW25N120R2FKSA1	PG-TO247-3
IHW30N110R3	SP000702510	IHW30N110R3FKSA1	PG-TO247-3
IHW30N120R3	SP000999768	IHW30N120R3FKSA1	PG-TO247-3
IHW30N135R3	SP000989496	IHW30N135R3FKSA1	PG-TO247-3
IHW30N160R2	SP000273701	IHW30N160R2FKSA1	PG-TO247-3
IHW40N120R3	SP000999770	IHW40N120R3FKSA1	PG-TO247-3
IHW40N135R3	SP000989498	IHW40N135R3FKSA1	PG-TO247-3